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ommissioner of Patents and Trademarks: Please record the attached original documents or copy thereof. 2. Name and address of receiving parties: 1. Name of conveying party(ies): Yueh-Liang LIU WINBOND ELECTRONICS CORP. Name: Additional name(s) of conveying parties attached? [] YES [X] NO Internal Address: 3. Nature of conveyance Street Address: No. 4, Creation Road III, [X] Assignment [] Merger Science-Based Industrial Park [] Security Agreement [] Change of Name City: Hsinchu State: Zip: \_\_\_\_ Country: Taiwan, R.O.C [] Other Additional name(s) & address(es) attached? []YES [X]NO Execution Date: March 6, 2000 4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: March 6, 2000 A. Patent Application No(s). B. Patent No(s).: Additional numbers attached? [] YES [X] NO 6. Total number of application and patents involved: [1] 5. Name and address of party to whom correspondence concerning document should be mailed: Richard P. Berg 7. Total fee 937 CFR 3.41).....\$ 40.00 LADAS & PARRY [X] Enclosed Internal Address: Any additional fees which may be required are Street Address: 5670 Wilshire Boulevard, #2100 [X] Authorized to be charged to deposit account City: Los Angeles State: CA Zip:90036-5679 No. <u>12-0415</u> COLUMBIA CHARLA / COMMONGS COLUMBIA 8. Deposit account number: (Attach duplicate copy of this page if paying by deposit account) DO NOT USE THIS SPACE Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Richard P. Berg April 13, 2000 Name of Person Signing Reg. No. 28,145 Total number of pages including cover sheet, attachments, and document: [ 2 ] plus \$40 check Mail documents to be recorded with required cover sheet information to: Commissioner of Patents and Trademarks **Box Assignments** Washington, D.C. 20231 Public burden reporting for this sample cover sheet is estimated to average about 30 minutes per document to be

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**PATENT** REEL: 010739 FRAME: 0071

## **ASSIGNMENT**

WHEREAS, Yuen-liang LIU
hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:
Title: MACHINE FOR EICHING THE EDGE OF A WAFER AND METHOD OF ETCHING THE EDGE OF A WAFER
Filed: Serial No
Filed: Serial No. Executed on: March 6, 2000
WHEREAS, <u>Winbond Electronics Corp.</u> of <u>No. 4, Creation</u> Rd. III, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.
hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;
NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.
Assignor further agrees/agree that he/she/they will, without charge to said Assignee but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request. to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.
IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.
Yueb-Lang LTI  Date:
Yueh-l and LII

**RECORDED: 04/13/2000** 

PATENT REEL: 010739 FRAME: 0072